

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT5220647

|                              |              |
|------------------------------|--------------|
| <b>SUBMISSION TYPE:</b>      | RESUBMISSION |
| <b>NATURE OF CONVEYANCE:</b> | ASSIGNMENT   |
| <b>RESUBMIT DOCUMENT ID:</b> | 504968570    |

**CONVEYING PARTY DATA**

| Name       | Execution Date |
|------------|----------------|
| HODONG LEE | 06/15/2018     |
| HOSHIK LEE | 06/15/2018     |

**RECEIVING PARTY DATA**

|                        |  |
|------------------------|--|
| <b>Name:</b>           | SAMSUNG ELECTRONICS CO., LTD.              |
| <b>Street Address:</b> | 129, SAMSUNG-RO, YEONGTONG-GU, GWEONGGI-DO |
| <b>City:</b>           | SUWON-SI                                   |
| <b>State/Country:</b>  | KOREA, REPUBLIC OF                         |
| <b>Postal Code:</b>    | 16677                                      |

**PROPERTY NUMBERS Total: 1**

| Property Type       | Number   |
|---------------------|----------|
| Application Number: | 16013055 |

**CORRESPONDENCE DATA**

Fax Number: (202)315-3758

*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

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|                                |                     |
|--------------------------------|---------------------|
| <b>ATTORNEY DOCKET NUMBER:</b> | 012052.1617         |
| <b>NAME OF SUBMITTER:</b>      | RANDALL S. SVIHLA   |
| <b>SIGNATURE:</b>              | /Randall S. Svihla/ |
| <b>DATE SIGNED:</b>            | 11/02/2018          |

**Total Attachments: 2**


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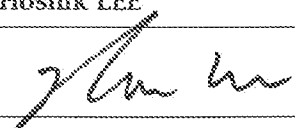
source=NONR20181026\_0120521617\_SupplementalExecutedCDAWithAppNumberForEPAS#page2.tif



**COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)**

In witness whereof, I, as a below-named inventor and assignor, intending to be legally bound, have hereunto affixed my signature on the date indicated below next to my signature.

|                           |   |      |               |
|---------------------------|---|------|---------------|
| Inventor's Legal Name     | Hodong LEE  |      |               |
| Inventor's Signature      |                                        | Date | June 15, 2018 |
| Residence (City, Country) | Yongin-si, Republic of Korea  |      |               |
| Mailing Address           | Samsung Advanced Institute of Technology, 130, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do 16678, Republic of Korea |      |               |

|                           |   |      |               |
|---------------------------|---|------|---------------|
| Inventor's Legal Name     | Hoshik LEE  |      |               |
| Inventor's Signature      |                                        | Date | June 15, 2018 |
| Residence (City, Country) | Seongnam-si, Republic of Korea  |      |               |
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